Date Created: 2008/08/20 Date Issued On: 2008/09/17

PCN#: Q3083402

## **INFORMATION ONLY NOTIFICATION**

This is to inform you that a minor change is being made to the following product(s). This notification is for your information only.

If you have any questions concerning this change, please contact:

**Technical Contact:** 

Name: Hong, JuHyung

E-mail: Juhyung.Hong@notes.fairchildsemi.com

Phone:

**PCN Originator:** 

Name: Hong, JuHyung

E-mail: Juhyung.Hong@notes.fairchildsemi.com

Phone:

Implementation of change:

Expected 1st Device Shipment Date: 2008/10/26

Earliest Year/Work Week of Changed Product: 0844

Change Type Description: Bond Wire Diameter

Description of Change (From): 15mil \* 1ea per chip(2chip), total 15mil 2ea

Description of Change (To): 20mil \* 2ea per chip(2chip), total 20mil 4ea

Reason for Change: Resolving Vf issued observed when affected devices were change from 2x

20mils Al-wire per die to 1x 15mils Al-wire per die.

Product Id Description: Some Schottky diodes devices packaged in TO220 & TO220F. The products affected by this change are listed below in the "Affected FSIDs" section

## Affected FSIDs:

| FYP1004DNTU   | FYP1010DNTU  | FYP1045DNTU      |
|---------------|--------------|------------------|
| FYP1504DNTU   | FYP1545DNTU  | FYP2004DNTU      |
| FYP2006DNTU   | FYP2010DNTU  | FYP2045DNTU      |
| FYPF1545DNTU  | FYPF2004DNTU | FYPF2006DNTU     |
| FYPF2010DNTU  | FYPF2045DNTU | MBR20S100CT      |
| MBR20S100CTTU | MBRP1545NTU  | MBRP2045NTU      |
| MBRP3010NTU   | MBRP3045NTU  | MBRP3045NTU_F080 |